

PPAP-200

Advanced Communication Appliance System Board

Specification

CPU

Support Intel® Socket 370 Pentium® III processor up to 1GHz and Celeron up to 850MHz

Chipset

Intel® 815E Chipset

Memory

Built-in one 144-pin SODIMM socket to support PC133/PC100 SDRAM up to 512MB memory size

LAN

Built-in two Intel® 82559ER and one Intel® 82801BA(w/82562ET) LAN ports

Expansion Support

One PCI connector for expansion

On-Board I/O

Two USB & two SIO ports

Application LEDs

Eight application definable LEDs

Hardware Monitor

Support on-board hardware monitor for one CPU fan, two system fan and the system voltages

Operating Temperature Range

5 to 45 °C, 20-90%RH

Storage Temperature Range

5 to 70°C, 5-95%RH

Dimension

130(W) x 216(L) mm

5.12"(W) x 8.5"(L)

Ordering Guide

PPAP-200

Advanced Communication Appliance system board based on Intel® 815E chipset with Three 10/100 Base-T Ethernet ports

Highlights

Scalable computing power from Intel® Celeron to Pentium® III processors to provide a wide range of price/performance selections

Adopt Intel's new generation 815E chipset

- Support 66/100/133 MHz FSB speed
- Support up to 512 MB PC100/133 SDRAM
- ATA-100 IDE for storage device

Three 10/100 Ethernet ports on board for advanced communication appliances

Tailor-made BIOS allows users to operate it as a communication device instead of a computer system

BIOS can be operated via SIO port

DOM is supported for embedded application

Eight application definable LEDs

